

Helping Customers Innovate, Improve & Grow

Table 1. Electrical Performance						
Parameter	Symbol	Min.	Тур	Max	Units	
Nominal Frequency	F _{NOM}	8.000		100.000	MHz	
Mode		Fundan	nental or 3rd Ov	vertone		
Operating Temperature Range	T _{OP}	0/70,-	°C			
Stability Over T _{op} ¹	F _{STAB}	±10		±100	ppm	
Frequency Tolerance ²	F _{TOL}		±10	±20	ppm	
Load Capacitance	C	6		32	pF	
Shunt Capacitance	C°			5	pF	
Drive Level			10	100	uW	
Aging / 1st year (at 25 °C)	F _{AGE}			±5	ppm	
Insulation Resistance		500			MOhm	
Storage Temperature	Т _{sto}	-40		90	°C	
	Equivalent Se	eries Resistance				
Crystal Frequency 8.000MHz-10.000MHz 10.001MHz-14.000MHz 14.001MHz-20.000MHz 20.001MHz-40.000MHz 40.000MHz-100.000MHz, 3rd Overtone	ESR			60 50 40 30 80	Ohm	

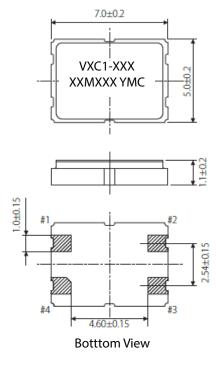
Notes:

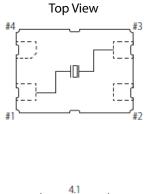
1. Referenced to the Frequency at 25 °C.

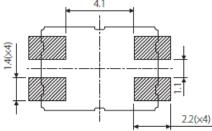
2. Frequency measured at 25 °C \pm 3 °C.

Product is compliant to RoHS directive and fully compatible with lead free assembly.

Package Drawing







All Dimensions in mm

Part Marking:

VXC1 -XXX = Product family and ordering options XXMXXX = Frequency Y = YearM = MonthA = January B = February C = March D = April E = MayF = June G = JulyH = August I = September

J = October

K = November

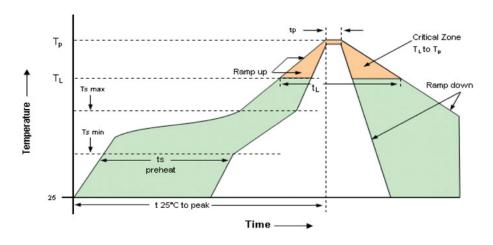
L = December

C = Manufacuting Location

Table 2. Pinout							
Pin	Function						
1	Crystal						
2	Connected to cover (Connect to GND						
3	Crystal						
4	Connected to cover (Connect to GND)						

Table 3. Environmental Compliance						
Parameter	Conditions					
Mechanical Shock	MIL-STD-883, Method 2002, Condition B					
Mechanical Vibration	MIL-STD-883, Method 2007, Condition A					
Temperature Cycle	MIL-STD-883, Method 1010, Condition B					
Solderability	MIL-STD-202-210, Condition B					
Gross and Fine Leak	MIL-STD-883, Method 1014					
Altitude	MIL-STD-883, Method 1001, Condition B					
Moisture Sensitivity Level	MSL 1					
Contact Pads	Gold (0.2 um min) over Nickel					
Weight	130 mg					

Reliability & IR Compliance



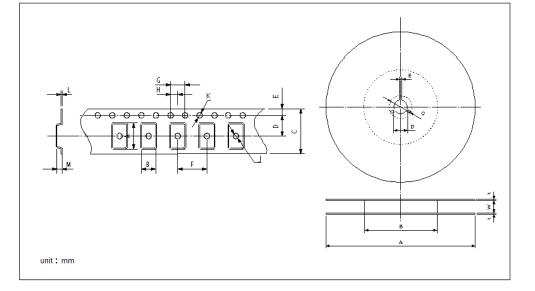
Solderprofile:

Table 4: Reflow Profile						
Parameter	Symbol	Value				
PreHeat Time Ts-min Ts-max	t _s	60 sec Min, 260 sec Max 150°C 200°C				
Ramp Up	R _{UP}	3 °C/sec Max				
Time Above 217 °C	t	60 sec Min, 150 sec Max				
Time To Peak Temperature	T _{AMB-P}	480 sec Max				
Time at 260 °C	t _e	30 sec Max				
Ramp Down	R _{DN}	6 °C/sec Max				

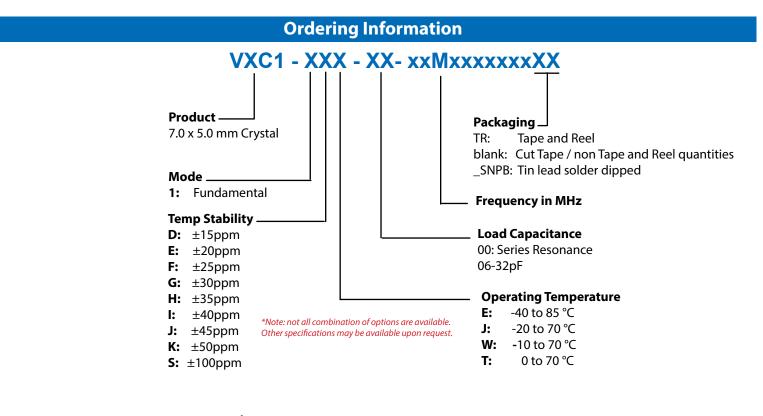
Pads are Au over Ni and compatible with either SnPb or Pb free attachment. MSL: 1

Tape & Reel

Table	Table 5. Tape and Reel Dimensions (mm)																	
Таре												Reel						
Α	В	С	D	E	F	G	Н	J	К	L	М	Α	В	С	D	Е	W	Т
7.3	5.3	16.0	7.5	1.75	8.0	4.0	2.0	1.5	1.5	0.3	1.9	180	60	21.0	13.0	2.0	16.5	1.5



1K pieces per reel

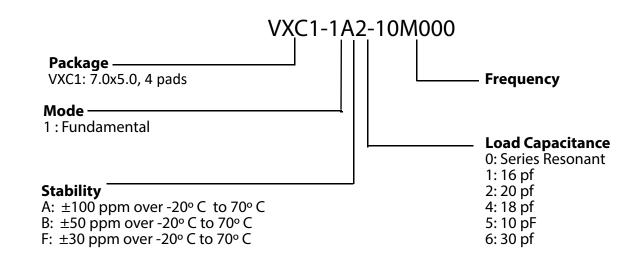


Example: VXC1-1EE-12-25M000000TR Tape and Reel VXC1-1EE-12-25M0000000 Cut Tape VXC1-1EE-12-25M0000000_SNPB Tin lead solder dipped

Revision History

Revision Date	Approved	Description				
August 30, 2016	RC	Initial datasheet for factory approval and release to customer.				
August 10, 2018	FB	Update logo and contact information, add "SNPBDIP" ordering option				
June 9, 2019	FB	Update logo and contact information, add Table 2 Environmental compliance, change "SNPBDIP" to "SNPB"				
April 30, 2020	FB	Add tape and reel ordering option, correct package drawing				

Previous Ordering Information for Reference Only Do Not Use to Build a New Part Number



The ordering codes for the VXC1 were changed in 2016. If you had ordered a specific code based off this ordering method, it is still available for purchase under the old code however no new part numbers will be created using this system.

Due to the change in the 8th character from numeric to alphabetic, there is no opportunity for overlap between the two ordering

Contact Information

USA: 100 Watts Street Mt Holly Springs, PA 17065 Tel: 1.717.486.3411 Fax: 1.717.486.5920 **Europe:** Landstrasse 74924 Neckarbischofsheim Germany Tel: +49 (0) 7268.801.0 Fax: +49 (0) 7268.801.281



Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your reasonability to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATION OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION INCLUDING, BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly, or otherwise, under any Microchip intellectual property rights unless otherwise stated.

Trademarks

The Microchip and Vectron names and logos are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.